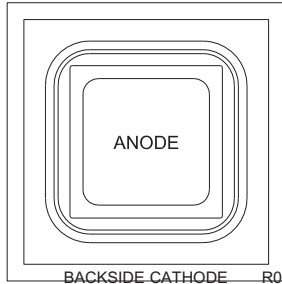


The CPZ28X-1N746A thru CPZ28X-1N759A are silicon Zener diodes ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

Die Size	13 x 13 MILS
Die Thickness	5.5 MILS
Anode Bonding Pad Size	7.0 x 7.0 MILS
Top Side Metalization	Ti/Al – 13,000Å
Back Side Metalization	Au-As – 9,000Å
Scribe Alley Width	1.97 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	101,184

MAXIMUM RATINGS:

Operating and Storage Junction Temperature

SYMBOL

T_J, T_{stg}

-65 to +150

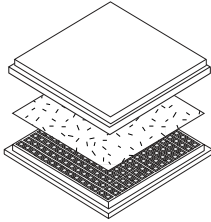
UNITS

°C

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$) $V_F=1.5\text{V MAX @ } I_F=200\text{mA}$ (for all types)

Type	Zener Voltage $V_Z @ I_{ZT}$			Test Current I_{ZT}	Maximum Zener Impedance $Z_{ZT} @ I_{ZT}$	Maximum Reverse Leakage Current $I_R @ V_R$		Maximum Regulator Current I_{ZM}
	MIN	NOM	MAX			I_R	V_R	
	V	V	V	mA	Ω	μA	V	mA
CPZ28X-1N746A	3.135	3.3	3.465	20	28	10	1.0	110
CPZ28X-1N747A	3.420	3.6	3.780	20	24	10	1.0	100
CPZ28X-1N748A	3.705	3.9	4.095	20	23	10	1.0	95
CPZ28X-1N749A	4.085	4.3	4.515	20	22	2.0	1.0	85
CPZ28X-1N750A	4.465	4.7	4.935	20	19	2.0	1.0	75
CPZ28X-1N751A	4.845	5.1	5.355	20	17	1.0	1.0	70
CPZ28X-1N752A	5.320	5.6	5.880	20	11	1.0	1.0	65
CPZ28X-1N753A	5.890	6.2	6.510	20	7.0	0.1	1.0	60
CPZ28X-1N754A	6.460	6.8	7.140	20	5.0	0.1	1.0	55
CPZ28X-1N755A	7.125	7.5	7.875	20	6.0	0.1	1.0	50
CPZ28X-1N756A	7.790	8.2	8.610	20	8.0	0.1	1.0	45
CPZ28X-1N757A	8.645	9.1	9.555	20	10	0.1	1.0	40
CPZ28X-1N758A	9.50	10	10.50	20	17	0.1	1.0	35
CPZ28X-1N759A	11.40	12	12.60	20	30	0.1	1.0	30

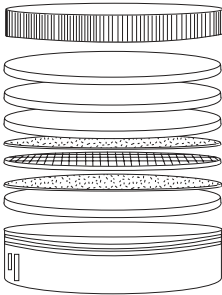
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

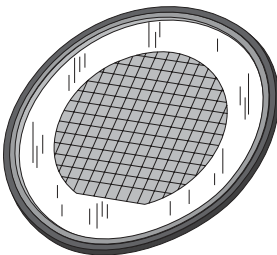
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

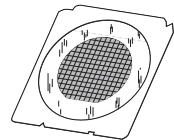
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centrasemi.com

Worldwide Field Representatives:
www.centrasemi.com/wwreps

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